参考資料

华能智研®
HALNZIYE
heat conduction system
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Data sheet of HY310

Introduction / 產品簡介

HY310 thermal pad
HY310 thermal silicone soft pad is a kind of silicone rubber-based gap filling material which is highly compressed with high heat-conducting filling materials.
The coefficient of heat conductivity can reach 3.2W/m・K. This kind of materials is aiming at offering superb heat-conducting property and maintains the cost efficiency of customers as well. The self-adhesion of HY310 enables them to stick on heating interfaces without back adhesives or binders. Apply HY310 heat-conducting silicone sheets with appropriate thickness to the gaps between heating interfaces and their components according to the different sizes of the heating interfaces and gaps to form seamless connections between the heating interfaces and related components.

HY310 has good thermal conductivity. Widely used in electrical and electronic cooling, power, transistors and thermistor thermal adhesive sealing, PTC bonding insulation.
Especially suitable for high performance requirements for thermal adhesive seal.
HY310 has excellent characteristics which are incombustibility, anti aging deterioration, extensive temperature (- 50 ～ +220 ℃) applicability, insulating, dampproofing, no swelling and etc. HY310 is for most metal and nonmetal and has good adhesion, capable of a variety of electronic components for sealing, bonding, solvent-free, it will not emit toxic gases, does not pollute the surrounding environment.

Features / 特性

- Appearance / 產品外觀 : Light gray
- 熱傳導系數 : > 3.2 W/m-k
- Breakdown Voltage : > 3000V
- Thickness : 0.5mm

Thermal silicone soft pad Uses: used in electrical and electronic products, control board, TFT-LCD, notebook computers, power supply,High efficiency LED lamp and other products, from thermal conductivity, filling, damping effect; can be added one-sided silicone cloth to enhance its mechanical properties, can be directly glued to the surface of the body parts without the need for reinforcement with the bolt and so on. (According to the different needs of customers into any shape of die-cut sheets can also be affixed adhesive or gluing).

Typical applications: Customers can heat body and heat sink the size of the gap between the selection of a suitable thickness of the thermal silica films, used in electronic products, electronic equipment, heating power devices (integrated circuits, power management, SCR, transformers, Power LEDs etc.) and the cooling facilities (heat sink, aluminum, etc.) in close contact, to achieve better thermal conductivity results.